

# 82V N-Channel Trench MOSFET(Preliminary)

### **General Description**

- Trench Power technology
- Low R<sub>DS(ON)</sub>
- Low Gate Charge
- Optimized for fast-switching applications

### **Applications**

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

### **Product Summary**

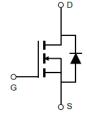
82V  $I_D$  (at  $V_{GS} = 10V$ ) 88A  $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) <8.5mΩ

100% UIS Tested









Part Number	Package Type	Form	Marking	
TTP88N08A	TO-220	Tube	TTP88N08A	

## Absolute Maximum Ratings (T<sub>A</sub> =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		V <sub>DS</sub>	82	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current B	T <sub>C</sub> =25°C	I <sub>D</sub>	88	٨	
	T <sub>C</sub> =100°C		66	A	
Pulsed Drain Current <sup>A</sup>		I <sub>DM</sub>	264	Α	
Avalanche Current A		I <sub>AS</sub>	43	Α	
Single Pulse Avalanche Energy L =0.3mH <sup>A</sup>		E <sub>AS</sub>	277	mJ	
lower Dissipation <sup>C</sup>	T <sub>C</sub> =25°C		174	W	
	T <sub>C</sub> =100°C	- P <sub>D</sub>	87	W	
Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 175	°C	

#### **Thermal Characteristics**

Parameter		Parameter		Symbol	Maximum	Units
Maximum Junction-to-Case	Steady-State	$R_{\Theta JC}$	0.86	00.04		
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	100	°C/W		



Electric	cal Characteristics(T <sub>J</sub> =25°C ur	nless otherwise r	noted)				
Cumbal	Doromotor	rameter Conditions		Value			11!1
Symbol	Parameter			Min	Тур	Max	Units
STATIC P	ARAMETERS					_	
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_{D} = 250 \mu A, V_{GS} = 0 V$		82	-		V
ı	Zero Gate Voltage Drain Current	V <sub>DS</sub> =82V, V <sub>GS</sub> =0V	T <sub>J</sub> =25°C	1	-	1	۸
I <sub>DSS</sub>	Zero Gate Voltage Drain Gurrent	$V_{DS} = 82V, V_{GS} = 0V$	T <sub>J</sub> =125°C	1	-	100	μA
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$		ŀ		±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2	3	4	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_{D} = 30A$		-	7.4	8.5	mΩ
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5V, I_{D} = 20A$		1	37		S
$V_{SD}$	Diode Forward Voltage	I <sub>S</sub> =30A, V <sub>GS</sub> =0V				1	V
I <sub>s</sub>	Maximum Body-Diode Continuous Current B					88	Α
DYNAMIC	PARAMETERS						-
C <sub>iss</sub>	Input Capacitance				5341		pF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0V, V_{DS} = 40V, f$	$V_{GS} = 0V, V_{DS} = 40V, f = 1MH_Z$		263		
C <sub>rss</sub>	Reverse Transfer Capacitance				241		
$R_g$	Gate Resistance	f =1MH <sub>Z</sub>	f =1MH <sub>Z</sub>		1.5		Ω
SWITCHIN	NG PARAMETERS						
$Q_g$	Total Gate Charge				100		
$Q_{gs}$	Gate Source Charge	$V_{GS} = 10V, V_{DS} = 40V, I$	$V_{GS} = 10V, V_{DS} = 40V, I_{D} = 20A$		25		nC
$Q_{gd}$	Gate Drain Charge				30		
t <sub>D(on)</sub>	Turn-On Delay Time				24		
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DS} = 40V, I_{D} = 20A,$ $R_{G} = 2.5\Omega$		1	19		ns
$T_{D(off)}$	Turn-Off Delay Time				70		
t <sub>f</sub>	Turn-Off Fall Time				30		
t <sub>rr</sub>	Body Diode Reverse Recovery Time	1 -200 d:/dt -4000/			37		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =20A, di/dt =100A/μs			58		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$  =175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

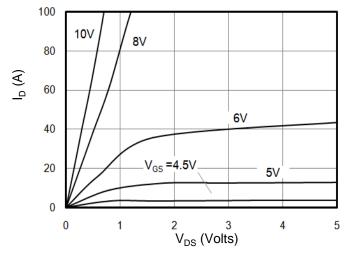


Figure 1: On-Region Characteristics

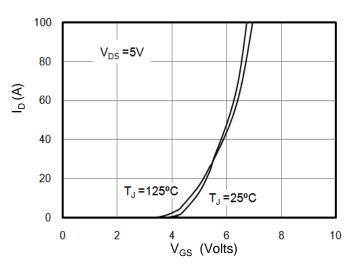


Figure 2: Transfer Characteristics

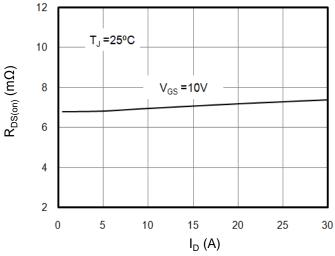
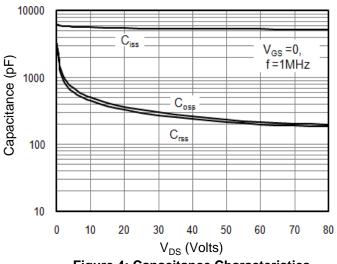


Figure 3: On-Resistance vs. Drain Current



**Figure 4: Capacitance Characteristics** 

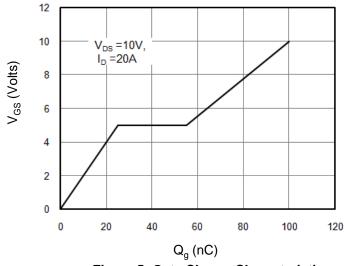


Figure 5: Gate Charge Characteristics

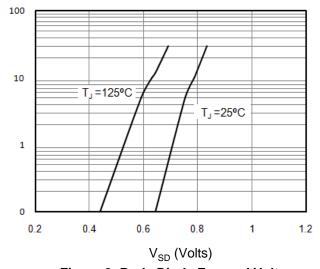


Figure 6: Body Diode Forward Voltage

I<sub>s</sub> (A)



#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

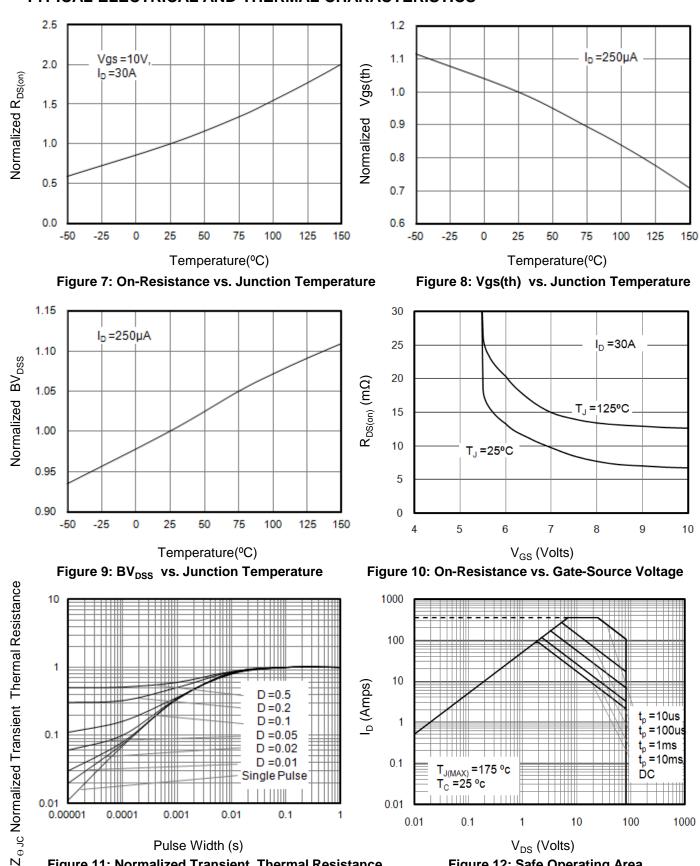


Figure 11: Normalized Transient Thermal Resistance

Pulse Width (s)

Figure 12: Safe Operating Area

V<sub>DS</sub> (Volts)



Figure A: Gate Charge Test Circuit and Waveforms

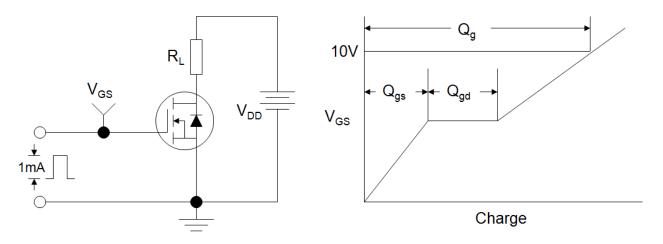


Figure B: Resistive Switching Test Circuit and Waveforms

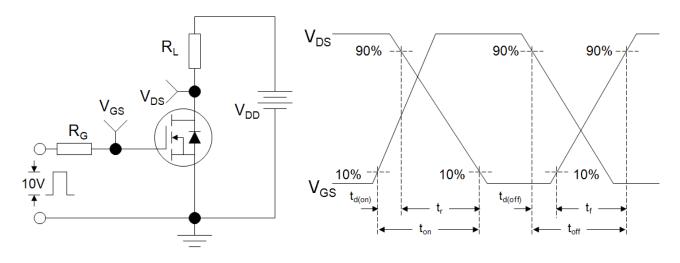
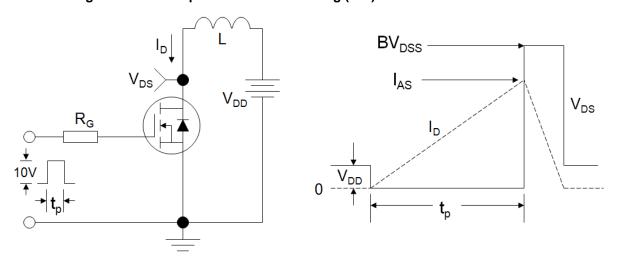
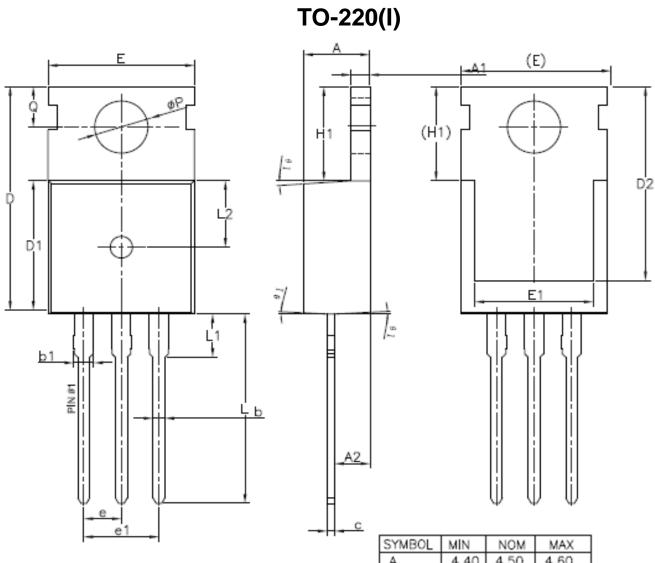
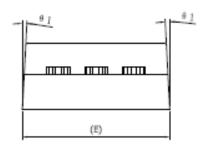


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms





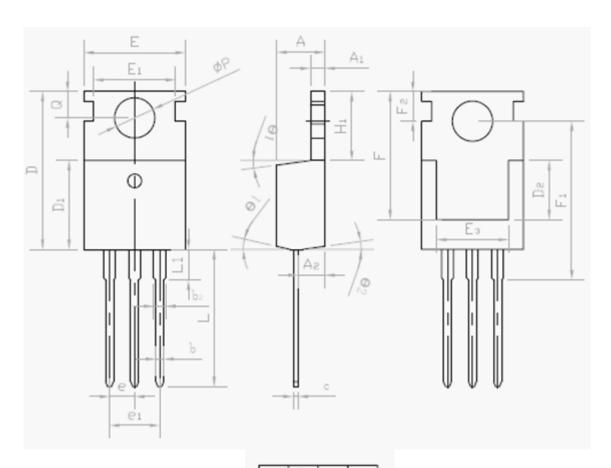




SYMBOL	MIN	NOM	MAX	
Α	4.40	4.50	4.60	
A1	1.27	1.30	1.33	
A2	2.30	2.40	2.50	
b	0.70	_	0.90	
b1	1.27	1	1.40	
С	0.45	0.50	0.60	
D	15.30	15.70	16.10	
D1	9.10	9.20	9.30	
D2	13.10	_	13.70	
Ε	9.70	9.90	10.20	
E1	7.80	8.00	8.20	
е	2	2.54BSC		
e1		5.08BSC	;	
H1	6.30	6.50	6.70	
L	12.78	13.08	13.38	
L1	_	_	3.50	
L2	4.60REF			
øΡ	3.55	3.60	3.65	
Q	2.73	_	2.87	
01	1*	3*	5*	



# TO-220(E)



A Aı A:	1.15	4.57	4.87		
_	1.15				
Α.	214.0	1.30	1.45		
~:	2.10	2.40	2.70		
ъ	0.70	0.80	1.00		
Ъ	1.17	1.27	1.50		
С	0.40	0.50	0.65		
D	15.10	15.60	16.10		
Di	8.80	9.10	9.40		
D:	5.70	6.70	7.00		
Ε	9.70	10,00	10.30		
Εı	-	8.70	-		
E:	9.63	10.00	10.35		
Ea	7.00	8.00	8.40		
e	2.54 BSC				
e:	5.08 BSC				
Ht	6.00	6.50	6.85		
L	12.75	13.50	13.90		
L1	-	3.10	3.40		
φP	3.45	3.60	3.75		
Q	2.60	2.80	3.00		
θ.	4*	7*	10*		
θ,	0.	3.	6*		
F	13.30	13.50	13.70		
P.	15.50	15.90	16.30		
F,	08.5	3.00	3.20		
	D   D   D   E   E   E   E   E   E   E	C 0.40 D 15.10 D1 8.80 D2 5.70 E 9.70 E1 - E2 9.63 E3 7.00 e 2: e1 5.70 L 12.75 L1 - #P 3.45 G 2.60 H 4* H 6.00 F 13.30 F 13.50	C 0.40 0.50 D 15.10 15.60 D1 8.80 9.10 D2 5.70 6.70 E 9.70 10.00 E1 - 8.70 E2 9.63 10.00 E3 7.00 8.00 C3 7.00 8.00 C4 12.75 13.50 L1 - 3.10 GP 3.45 3.60 G 2.60 2.80 G 4* 7* G2 0* 3* F 13.50 13.50 F 13.50 15.50		



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